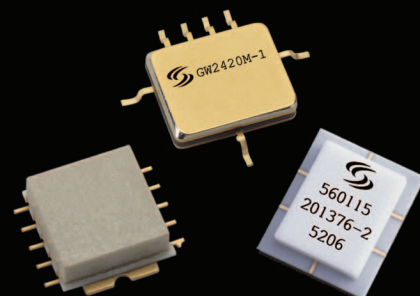
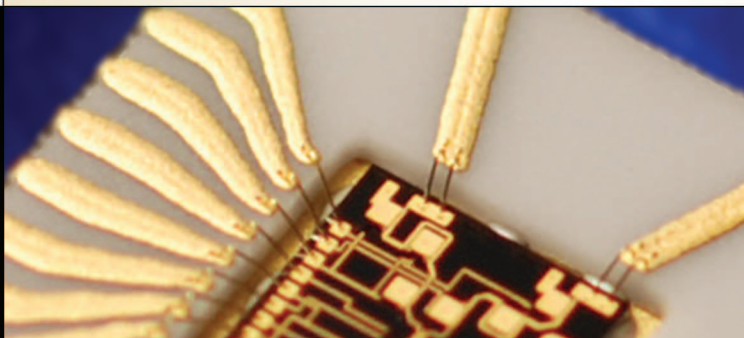




ASSEMBLY AND TEST OF HIGH FREQUENCY DEVICES

HIGH FREQUENCY
AND
HIGH SPEED
PACKAGING

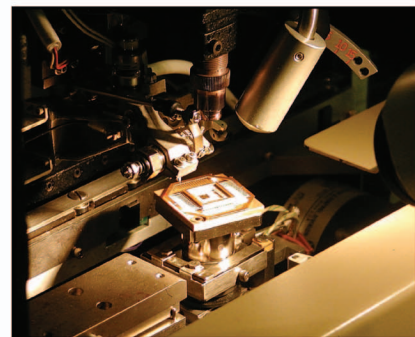


Since 2000, StratEdge has provided its customers assembly and test services for single- and multi-chip MMICs operating from DC to 50 GHz. Precision placement and attachment of high frequency and high speed microelectronic devices into packages must be done correctly to get maximum performance from these devices. That's where you benefit from StratEdge's years of packaging expertise, Class 1000 cleanroom with Class 100 work areas, and complete assembly and test facilities in San Diego, California. StratEdge performs eutectic or epoxy die and passive component attachment plus automatic wire bonding that ensures consistent loop lengths for the best electrical performance.

After assembly, the packages are lidded, leads trimmed and formed, and then tested with a HP 8510C network analyzer at up to 50 GHz. Post assembly services include serialization, labeling, bulk packaging, and preparation for delivery. StratEdge can accommodate special requests such as grouping completed parts based on tight electrical performance specifications. Environmental testing per MIL-STD-883 is also available. StratEdge is an ISO 9001 facility.

ASSEMBLY EQUIPMENT:

- **Mullen Equipment Company manual eutectic die bonders**
- **Westbond 7200A semi-automatic epoxy attach machine**
- **Yield Engineering Glen-R3A multi-rack RF plasma cleaner**
- **K&S 1474 fully automatic gold wedge wire bonders w/ pattern recognition software and boat and magazine handling equipment**
- **Hybond 572 manual gold wedge wire bonder**
- **Blue M 0V-18A forced convection drying oven**
- **Blue M DC-4580 curing oven**



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